

## ABSTRACT OF THE DISCLOSURE

### Molding Apparatus

Molding apparatus (200) is provided for simultaneously molding a molding  
 5 material around a number of separate substrates, each substrate having a  
 semiconductor chip mounted thereon. The apparatus includes a mold holder  
 (113a, 113b, 114, 103) having a first holding section for holding a first mold half  
 (119) and a second holding section for holding a second mold half (120). The  
 first and second holding sections have a common support surface (135), the  
 10 support surface (135) including a first movable member (104a) in the first  
 holding section and a second movable member (104b) in the second holding  
 section. The first and second movable members (104a, 104b) are movable  
 between a first position in which they protrude out of the support surface (135)  
 and a second position in which the protrusion from the support surface (135) is  
 15 less than in the first position. A first drive mechanism (100, 110) is coupled to  
 the first movable member (104a) and a second drive mechanism (100, 110) is  
 coupled to the second movable member (104b). The first and second drive  
 mechanisms (100, 110) are adapted to be independently actuated to move the  
 first and second movable members (104a, 104b) between the first and second  
 20 positions.